

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Prior Application: J. TANAKA et al et al  
Serial No. 10/179,214  
Filed: June 26, 2002

Group Art Unit: 2815  
Examiner: S. Clark  
For: RESIN-ENCAPSULATED SEMICONDUCTOR  
APPARATUS AND PROCESS FOR ITS  
FABRICATION

INFORMATION DISCLOSURE STATEMENT

Commissioner for Patents  
Alexandria, VA 22314

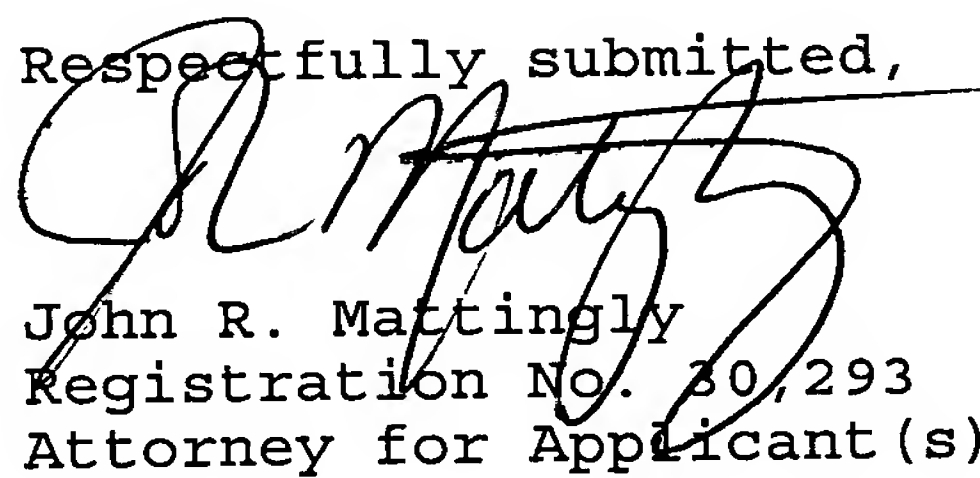
Sir:

In accordance with the duty of disclosure, Applicants inform the Examiner of the documents cited during prosecution of the parent application, USSN 10/179,214.

This is a continuation application of U.S. Serial No. 10/179,214, filed on June 26, 2002, which is a continuation application of U.S. Serial No. 09/969,847, filed October 4, 2001, now U.S. Patent No. 6,465,827, which is a continuation application of U.S. Serial No. 09/689,802, filed October 13, 2000, now U.S. Patent No. 6,441,416, which is a continuation application of U.S. Serial No. 09/665,062, filed September 19, 2000, abandoned, which is a divisional application of U.S. Serial No. 09/012,104, filed January 22, 1998, now U.S. Patent No. 6,147,374. This application is related to application Serial No. 09/969,848, filed October 4, 2001, now U.S. Patent No. 6,525,359, from which priority is claimed under 35 U.S.C. § 120.

The applicants request the Examiner to initial and return a copy of the attached PTO-1449 form as an indication that the references have been considered.

Respectfully submitted,



John R. Mattingly  
Registration No. 30,293  
Attorney for Applicant(s)

MATTINGLY, STANGER & MALUR  
1800 Diagonal Road, Suite 370  
Alexandria, Virginia 22314  
(703) 684-1120  
Date: September 29, 2003

FORM PTO-1449 (REV. 7-80)		U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE		ATTY. DOCKET NO. HIT 2 925-08	SERIAL NO.		
<b>LIST OF DOCUMENTS CITED BY APPLICANT</b> <i>(Use several sheets if necessary)</i>				APPLICANT J. TANAKA et al			
				FILING DATE 09/29/03		GROUP 2815	
<b>U.S. PATENT DOCUMENTS</b>							
* EXAMINER INITIAL	DOCUMENT	DATE	NAME	CLASS	SUBCLASS	FILING DATE <i>(If Appropriate)</i>	
	AA	5,563,762	10/1996	Leung et al			
	AB	5,117,272	05-1992	Nomura et al			
	AC	5,310,863	05-1994	Sachdev			
	AD	6,071,755	06-2000	Baba et al			
	AE	6,106,906	08-2000	Matsuda et al			
	AF	5,296,716	03-1994	Ovashinsky et al			
	AG	4,132,823	1/2/79	Blackwell et al			
	AH	6,465,827	10/2002	Tanaka et al			
	AI						
	AJ						
	AK						
<b>FOREIGN PATENT DOCUMENTS</b>							
	DOCUMENT	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION	
						YES	NO
	AL	8-124917	05-1996	Japan		<input type="checkbox"/>	<input type="checkbox"/>
	AM	7-278301	10-1995	Japan		<input type="checkbox"/>	<input type="checkbox"/>
	AN	07-221259	8/18/95	Japan		<input type="checkbox"/>	<input type="checkbox"/>
	AO	09-293837	11/11/97	Japan		<input type="checkbox"/>	<input type="checkbox"/>
	AP					<input type="checkbox"/>	<input type="checkbox"/>
<b>OTHER DOCUMENTS</b> <i>(Including Author, Title, Date, Pertinent Pages, etc.)</i>							
	AR	Lecture Collections in '96 Ferroelectric Film Memory Technique Forum, Science Forum, Inc., page 4-4, lines 1-12, Ishihara, January 26, 1996.					
	AS	Epoxy Molding Compounds for Semiconductor Devices, Thermosetting Resins, Vol. 13, No. 4, page 37, right column, lines 8-23, Ogata et al, 1992.					
	AT	Packaging Technique for Surface Mount Type LSI Packages and Improvements in Its Reliability, page 451, edited by Hitachi, Ltd.					
EXAMINER				DATE CONSIDERED			
<small>* EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.</small>							

FORM PTO-1449 (REV. 7-80)	U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE	ATTY. DOCKET NO. HIT 2 925-08	SERIAL NO.
LIST OF DOCUMENTS CITED BY APPLICANT (Use several sheets if necessary)		APPLICANT J. TANAKA et al	
		FILING DATE 09/29/03	GROUP 2815

U.S. PATENT DOCUMENTS

* EXAMINER INITIAL		DOCUMENT	DATE	NAME	CLASS	SUBCLASS	FILING DATE (If Appropriate)
	AA						
	AB						
	AC						
	AD						
	AE						
	AF						
	AG						
	AH						
	AI						
	AJ						
	AK						

FOREIGN PATENT DOCUMENTS

		DOCUMENT	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION	
							YES	NO
	AL						<input type="checkbox"/>	<input type="checkbox"/>
	AM						<input type="checkbox"/>	<input type="checkbox"/>
	AN						<input type="checkbox"/>	<input type="checkbox"/>
	AO						<input type="checkbox"/>	<input type="checkbox"/>
	AP						<input type="checkbox"/>	<input type="checkbox"/>

OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, etc.)

	AR		A Study of Package Cracking During the Reflow Soldering Process, "A" Edition, Vol. 55, No. 510, Kitano et al, 1989-2.
	AS		Effects of Mold Compound Properties on Lead-on-Chip (LOC) Package Reliability During IR Reflow, 1996 Electronic Components and Technology Conference, Yang et al.
	AT		

EXAMINER	DATE CONSIDERED
----------	-----------------

\* EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.